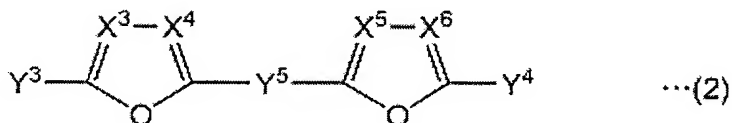
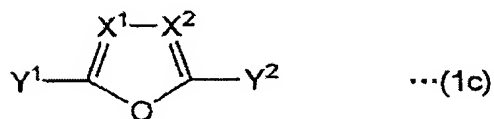
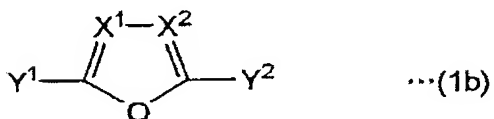
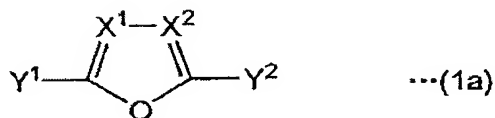
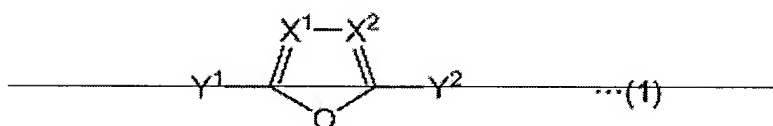


LISTING OF CLAIMS:

The present listing of claims replaces all prior listings or versions of claims in the present application.

1. (Currently Amended) A photosensitive resin composition comprising:
- (A) a binder polymer;
- (B) a photopolymerizing compound with an ethylenic unsaturated bond;
- (C) a photopolymerization initiator; and
- (D) a compound represented by the following general formula (1a), (1b), (1c), or (2),

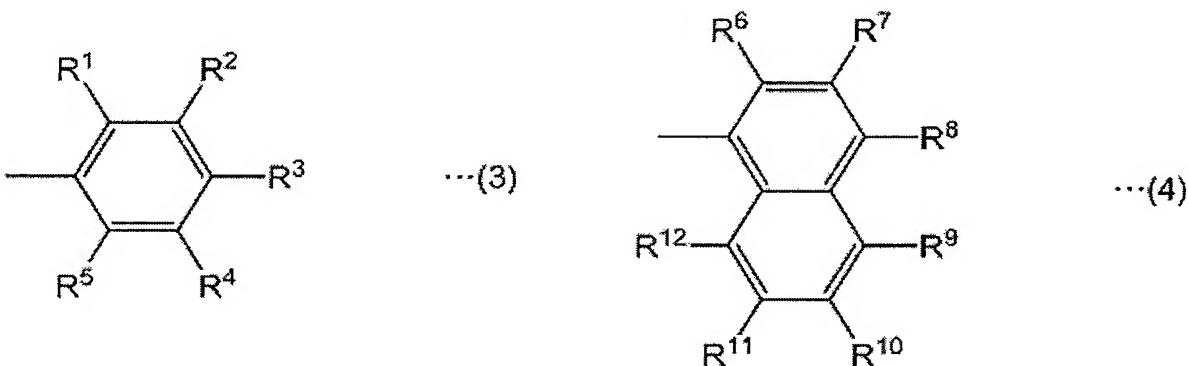


_____wherein

_____ in formula (1a), X^1 represents a CH group, a CCH_3 group, a CC_2H_5 group, or nitrogen, X^2 represents a CH group, a CCH_3 group, or a CC_2H_5 group, and Y^1 and Y^2 represent mutually different optionally substituted aryl;

_____ in formula (1b), X^1 and X^2 both represent nitrogen, and Y^1 and Y^2 represent mutually different optionally substituted aryl;

_____ in formula (1c), X^1 and X^2 both represent nitrogen and Y^1 and Y^2 both represent mutually the same group represented by formula (3) or formula (4)



wherein in formulae (3) and (4), at least one of R_1 , R_2 , R_3 , R_4 , R_5 , R_6 , R_7 , R_8 , R_9 , R_{10} , R_{11} , R_{12} represents C1-20 alkyl and the other represent hydrogen; and

_____ in formula (2), X^3 , X^4 , X^5 and X^6 each independently represent a CH group, a CCH_3 group, a CC_2H_5 group or nitrogen, Y^1 , Y^2 , Y^3 and Y^4 each independently represent optionally substituted aryl, and Y^5 represents optionally substituted arylene.

2. (Original) A photosensitive resin composition according to claim 1, wherein component (C) contains a 2,4,5-triarylimidazole dimer.

3. (Previously Presented) A photosensitive resin composition according to claim 1, wherein component (B) contains a bisphenol A-type (meth)acrylate compound.

4. (Previously Presented) A photosensitive resin composition according to claim 1, wherein the acid value of component (A) is 30-200 mg KOH/g and the weight-average molecular weight is 20,000-300,000.

5. (Previously Presented) A photosensitive resin composition according to claim 1, wherein the component (A) content is 20-90 parts by weight, the component (B) content is 10-80 parts by weight, the component (C) content is 0.01-20 parts by weight and the component (D) content is 0.001-20 parts by weight, with respect to 100 parts by weight as the total of component (A) and component (B).

6. (Previously Presented) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 1 formed on the support.

7. (Previously Presented) A resist pattern forming method comprising the steps of:
laminating a photosensitive resin composition layer for a photosensitive element according to claim 6 on a circuit forming board;
irradiating prescribed sections of the photosensitive resin composition layer with active light rays for photocuring of exposed sections; and then
removing non-exposed sections.

8. (Previously Presented) A process for manufacturing a printed circuit board comprising the steps of etching or plating a circuit forming board having a resist pattern formed thereon by a resist pattern forming method according to claim 7.

9. (Previously Presented) A photosensitive resin composition according to claim 2, wherein component (B) contains a bisphenol A-type (meth)acrylate compound.

10. (Previously Presented) A photosensitive resin composition according to claim 9, wherein the acid value of component (A) is 30-200 mg KOH/g and the weight-average molecular weight is 20,000-300,000.

11. (Previously Presented) A photosensitive resin composition according to claim 2, wherein the acid value of component (A) is 30-200 mg KOH/g and the weight-average molecular weight is 20,000-300,000.

12. (Previously Presented) A photosensitive resin composition according to claim 3, wherein the acid value of component (A) is 30-200 mg KOH/g and the weight-average molecular weight is 20,000-300,000.

13. (Previously Presented) A photosensitive resin composition according to claim 2, wherein the component (A) content is 20-90 parts by weight, the component (B) content is 10-80 parts by weight, the component (C) content is 0.01-20 parts by weight and the component (D) content is 0.001-20 parts by weight, with respect to 100 parts by weight as the total of component (A) and component (B).

14. (Previously Presented) A photosensitive resin composition according to claim 3, wherein the component (A) content is 20-90 parts by weight, the component (B) content is 10-80 parts by weight, the component (C) content is 0.01-20 parts by weight and the

component (D) content is 0.001-20 parts by weight, with respect to 100 parts by weight as the total of component (A) and component (B).

15. (Previously Presented) A photosensitive resin composition according to claim 4, wherein the component (A) content is 20-90 parts by weight, the component (B) content is 10-80 parts by weight, the component (C) content is 0.01-20 parts by weight and the component (D) content is 0.001-20 parts by weight, with respect to 100 parts by weight as the total of component (A) and component (B).

16. (Previously Presented) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 2 formed on the support.

17. (Previously Presented) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 3 formed on the support.

18. (Previously Presented) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 4 formed on the support.

19. (Previously Presented) A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to claim 5 formed on the support.

20. (New) A photosensitive resin composition comprising:

(A) a binder polymer;

(B) a photopolymerizing compound with an ethylenic unsaturated bond;

(C) a photopolymerization initiator; and

(D) one or more compounds selected from the group consisting of 2,5-diphenylfuran, 2,5-diphenyl-3,4-dimethylfuran, 2,5-diphenyl-3-ethylfuran, 2,5-di(p-methylphenyl)furan, 2,5-di(2,4-dimethylphenyl)furan, 2,5-di(p-butylphenyl)furan, 2,5-di(p-benzylphenyl)furan, 2-phenyl-5-(p-biphenyl)furan, 2,5-di(p-biphenyl)furan, 2-phenyl-5-(α -naphthyl)furan, 2,5-diphenyloxazole, 2,5-diphenyl-3-methyloxazole, 2,5-di(p-isopropylphenyl)oxazole, 1,4-bis(2-(5-phenyloxazolyl))benzene, 1,4-bis(2-(4-methyl-5-phenyloxazolyl))benzene, 2-phenyl-5-(p-biphenyl)oxazole, 2-phenyl-5-(α -naphthyl)oxazole, 2,5-di(α -naphthyl)oxazole, 1,4-bis(2-(5-phenyloxazolyl))naphthalene, 2,5-di(α -naphthyl)-1,3,4-oxadiazole, 2-phenyl-5-(α -naphthyl)-1,3,4-oxadiazole, 2,5-di(p-t-butylphenyl)-1,3,4-oxadiazole, 2,5-di(4-methyl-1-naphthyl)-1,3,4-oxadiazole, 2-phenyl-5-(p-biphenyl)-1,3,4-oxadiazole, 2-(4-biphenyl)-5-(4-t-butylphenyl)-1,3,4-oxadiazole, and 1,4-bis(2-(5-phenyl-1,3,4-oxadiazolyl))benzene.